# Pattern exposure order dependence in hydrogen silsesquioxane Devin K. Brown, Institute for Electronics and Nanotechnology, Georgia Institute of Technology

### Motivation

Pattern order dependence is observed and characterized in electron beam lithography (EBL) exposed hydrogen silsesquioxane (HSQ) resist. Previously, HSQ has been reported to have a time delay effect<sup>[1]</sup> which could autocorrelate to pattern order depending on the time required to expose the pattern. However, this observed effect is different, whereby the HSQ is sensitive to exposure order and location, is repeatable over time, and not a function of delay time. Previous work<sup>[2],[3]</sup> has identified pattern order dependence, but the mechanism is yet to be fully explained.





devin.brown@ien.gatech.edu





— 20 um

Figure 3: SEM image of 27 nm dots on 100 nm dose =  $5,000 \text{ uC/cm}^2$ , develop 25% TMAH 30 sec

# Conclusions

The following are new conclusions of this work compared to previous work. • the effect is not observed in PMMA, and thus indicates a chemical mechanism distinct to HSQ

• the effect is observed at both micron scale (10 um squares) and nanometer scale (27 nm dots on 100 nm pitch) binary lithography • the presence of heat before or after exposure is not responsible for the lower observed height, and therefore the effect cannot be caused by local beam heating • the first exposed square does not have the Si-H bond present at 2256 cm<sup>-1</sup> Raman spectroscopy wavelength indicating lower H concentration

## References

<sup>[1]</sup> D.A. Westly, J Vac Sci Technol B 29 (2011) <sup>[2]</sup>J. Liddle, J. Vac. Sci. Technol. B 21 (6), Nov/Dec 2003 <sup>[3]</sup>D.Olynick J. Vac. Sci. Technol. B 28 (3), May/Jun 2010

